

DATA SHEET

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74ALVCH16501

18-bit universal bus transceiver (3-State)

Product specification
Supersedes data of 1998 Aug 31
IC24 Data Handbook

1998 Sep 29

18-bit universal bus transceiver (3-State)

74ALVCH16501

FEATURES

- Complies with JEDEC standard no. 8-1A.
- CMOS low power consumption
- Direct interface with TTL levels
- Current drive ± 24 mA at 3.0 V
- Universal bus transceiver with D-type latches and D-type flip-flops capable of operating in transparent, latched or clocked mode.
- All inputs have bushold circuitry
- Output drive capability 50 Ω transmission lines @ 85°C
- 3-State non-inverting outputs for bus oriented applications

DESCRIPTION

The 74ALVCH16501 is an 18-bit universal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. Data flow in each direction is controlled by output enable (OE_{AB} and \overline{OE}_{BA}), latch enable (LE_{AB} and LE_{BA}), and clock (CP_{AB} and CP_{BA}) inputs. For A-to-B data flow, the device operates in the transparent mode when LE_{AB} is High. When LE_{AB} is Low, the A data is latched if CP_{AB} is held at a High or Low logic level. If LE_{AB} is Low, the A-bus data is stored in the latch/flip-flop on the Low-to-High transition of CP_{AB} . When OE_{AB} is High, the outputs are active. When OE_{AB} is Low, the outputs are in the high-impedance state.

Data flow for B-to-A is similar to that of A-to-B but uses \overline{OE}_{BA} , LE_{BA} and CP_{BA} . The output enables are complimentary (OE_{AB} is active High, and OE_{BA} is active Low).

To ensure the high impedance state during power up or power down, \overline{OE}_{BA} should be tied to V_{CC} through a pullup resistor and OE_{AB} should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}\text{C}$; $t_r = t_f = 2.5\text{ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT	
t_{PHL}/t_{PLH}	Propagation delay An, Bn to Bn, An	$V_{CC} = 2.5\text{V}$, $C_L = 30\text{pF}$ $V_{CC} = 3.3\text{V}$, $C_L = 50\text{pF}$	2.8 3.0	ns	
$C_{I/O}$	Input/output capacitance		8.0	pF	
C_I	Input capacitance		4.0	pF	
C_{PD}	Power dissipation capacitance per latch	$V_I = \text{GND to } V_{CC}^1$	Outputs enabled	21	pF
			Outputs disabled	3	

NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW):
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; C_L = output load capacitance in pF;
 f_o = output frequency in MHz; V_{CC} = supply voltage in V; $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

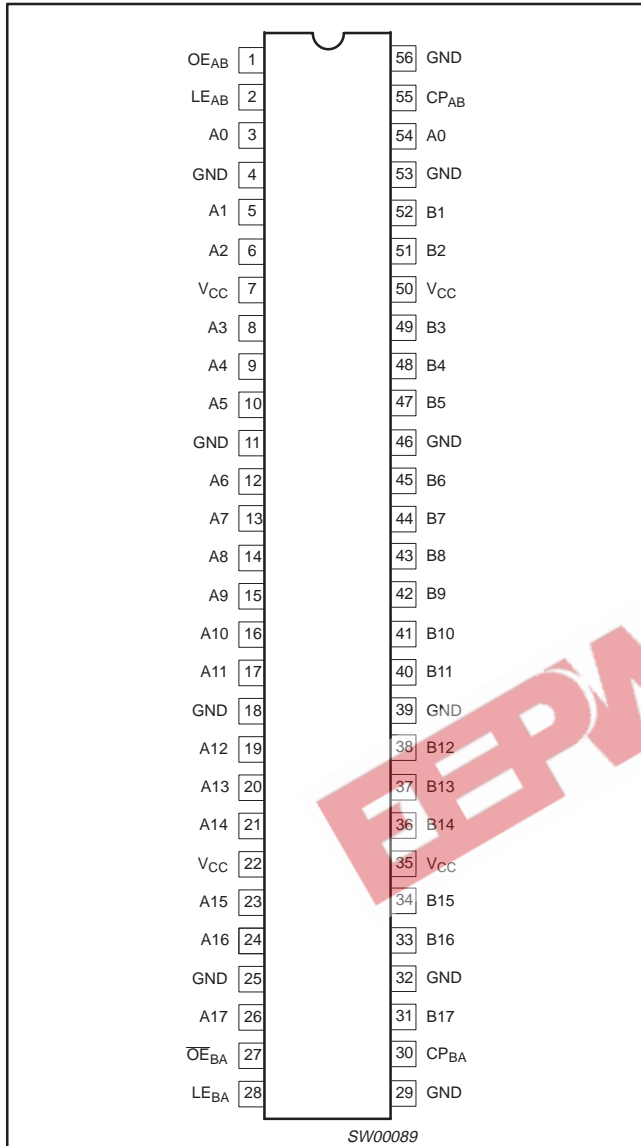
ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	DWG NUMBER
56-Pin Plastic TSSOP Type II	$-40^{\circ}\text{C to } +85^{\circ}\text{C}$	74ALVCH16501 DGG	SOT364-1

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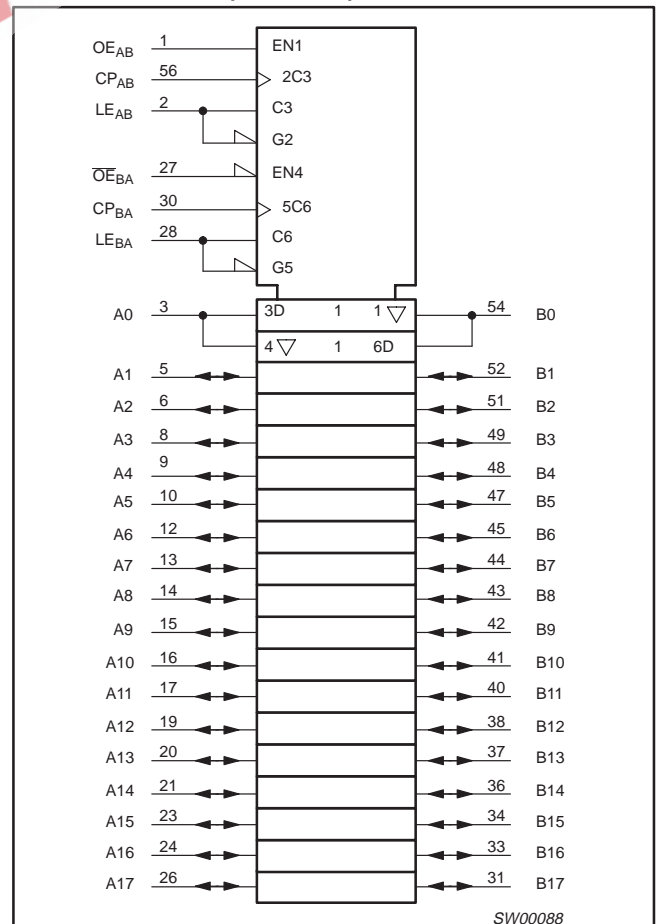
PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	OE _{AB}	Output enable A-to-B
2	LE _{AB}	Latch enable A-to-B
3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26	A0 to A17	Data inputs/outputs
4, 11, 18, 25, 29, 32, 39, 46, 53, 56	GND	Ground (0V)
7, 22, 35, 50	V _{CC}	Positive supply voltage
27	OE _{BA}	Output enable B-to-A
28	LE _{BA}	Latch enable B-to-A
30	CP _{BA}	Clock input B-to-A
54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31	B0 to B17	Data inputs/outputs
55	CP _{AB}	Clock input A-to-B

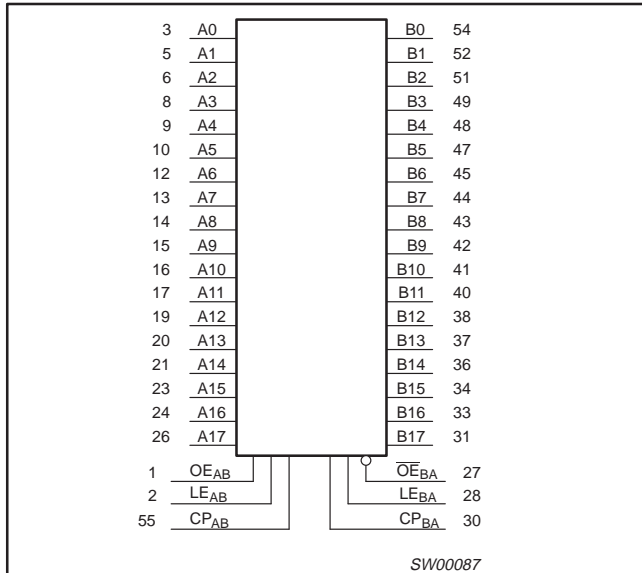
LOGIC SYMBOL (IEEE/IEC)



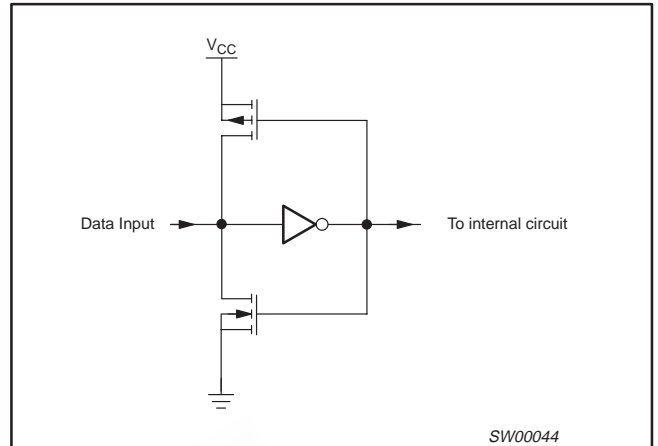
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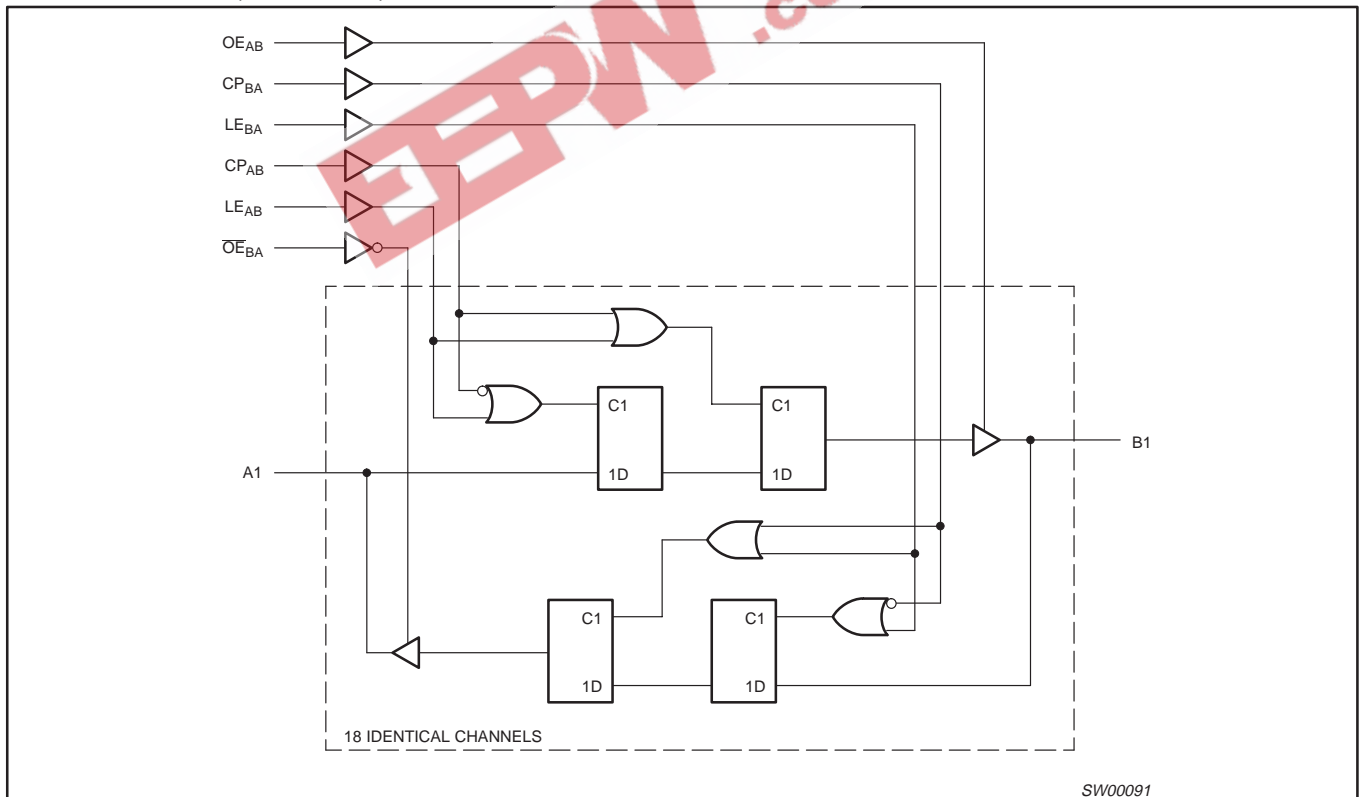
LOGIC SYMBOL



BUS HOLD CIRCUIT



LOGIC DIAGRAM (one section)



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FUNCTION TABLE

INPUTS				OUTPUTS	OPERATING MODE
OEAB	LEAB	CPAB	An	Bn	
L	X	X	X	Z	Disabled
H	H	X	H	H	Transparent
H	H	X	L	L	
H	↓	X	h	H	Latch data & display
H	↓	X	l	L	
H	L	↑	h	H	Clock data & display
H	L	↑	l	L	
H	L	H or L	X	H	Hold data & display
H	L	H or L	X	L	

NOTE: A-to-B data flow is shown; B-to-A flow is similar but uses \overline{OEBA} , LEBA, and CPBA.

H = High voltage level

h = High voltage level one set-up time prior to the Enable or Clock transition

L = Low voltage level

l = Low voltage level one set-up time prior to the Enable or Clock transition

NC= No Change

X = Don't care

Z = High Impedance "off" state

↓ = High-to-Low Enable or Clock transition

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIMITS		UNIT
			MIN	MAX	
V_{CC}	DC supply voltage 2.5V range (for max. speed performance @ 30 pF output load)		2.3	2.7	V
	DC supply voltage 3.3V range (for max. speed performance @ 50 pF output load)		3.0	3.6	
V_I	DC Input voltage range		0	V_{CC}	V
V_O	DC output voltage range		0	V_{CC}	V
T_{amb}	Operating free-air temperature range		-40	+85	°C
t_r, t_f	Input rise and fall times	$V_{CC} = 2.3$ to $3.0V$ $V_{CC} = 3.0$ to $3.6V$	0	20	ns/V
			0	10	

ABSOLUTE MAXIMUM RATINGS

In accordance with the Absolute Maximum Rating System (IEC 134)

Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		-0.5 to +4.6	V
I_{IK}	DC input diode current	$V_I < 0$	-50	mA
V_I	DC input voltage	For control pins ¹	-0.5 to +4.6	V
		For data inputs ¹	-0.5 to $V_{CC} + 0.5$	
I_{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
V_O	DC output voltage	Note 1	-0.5 to $V_{CC} + 0.5$	V
I_O	DC output source or sink current	$V_O = 0$ to V_{CC}	±50	mA
I_{GND}, I_{CC}	DC V_{CC} or GND current		±100	mA
T_{stg}	Storage temperature range		-65 to +150	°C
P_{TOT}	Power dissipation per package -plastic thin-medium-shrink (TSSOP)	For temperature range: -40 to +125 °C above +55°C derate linearly with 8 mW/K	600	mW

NOTE:

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Temp = -40°C to +85°C			
			MIN	TYP ¹	MAX	
V _{IH}	HIGH level Input voltage	V _{CC} = 2.3 to 2.7V	1.7	1.2		V
		V _{CC} = 2.7 to 3.6V	2.0	1.5		
V _{IL}	LOW level Input voltage	V _{CC} = 2.3 to 2.7V		1.2	0.7	V
		V _{CC} = 2.7 to 3.6V		1.5	0.8	
V _{OH}	HIGH level output voltage	V _{CC} = 2.3 to 3.6V; V _I = V _{IH} or V _{IL} ; I _O = -100μA	V _{CC} - 0.2	V _{CC}		V
		V _{CC} = 2.3V; V _I = V _{IH} or V _{IL} ; I _O = -6mA	V _{CC} - 0.3	V _{CC} - 0.08		
		V _{CC} = 2.3V; V _I = V _{IH} or V _{IL} ; I _O = -12mA	V _{CC} - 0.6	V _{CC} - 0.26		
		V _{CC} = 2.7V; V _I = V _{IH} or V _{IL} ; I _O = -12mA	V _{CC} - 0.5	V _{CC} - 0.14		
		V _{CC} = 3.0V; V _I = V _{IH} or V _{IL} ; I _O = -12mA	V _{CC} - 0.6	V _{CC} - 0.09		
		V _{CC} = 3.0V; V _I = V _{IH} or V _{IL} ; I _O = -24mA	V _{CC} - 1.0	V _{CC} - 0.28		
V _{OL}	LOW level output voltage	V _{CC} = 2.3 to 3.6V; V _I = V _{IH} or V _{IL} ; I _O = 100μA		GND	0.20	V
		V _{CC} = 2.3V; V _I = V _{IH} or V _{IL} ; I _O = 6mA		0.07	0.40	V
		V _{CC} = 2.3V; V _I = V _{IH} or V _{IL} ; I _O = 12mA		0.15	0.70	V
		V _{CC} = 2.7V; V _I = V _{IH} or V _{IL} ; I _O = 12mA		0.14	0.40	
		V _{CC} = 3.0V; V _I = V _{IH} or V _{IL} ; I _O = 24mA		0.27	0.55	
I _I	Input leakage current	V _{CC} = 2.3 to 3.6V; V _I = V _{CC} or GND		0.1	5	μA
I _{OZ}	3-State output OFF-state current	V _{CC} = 2.7 to 3.6V; V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND		0.1	10	μA
I _{CC}	Quiescent supply current	V _{CC} = 2.3 to 3.6V; V _I = V _{CC} or GND; I _O = 0		0.2	40	μA
ΔI _{CC}	Additional quiescent supply current	V _{CC} = 2.3V to 3.6V; V _I = V _{CC} - 0.6V; I _O = 0		150	750	μA
I _{BHL}	Bus hold LOW sustaining current	V _{CC} = 2.3V; V _I = 0.7V ²	45	-		μA
		V _{CC} = 3.0V; V _I = 0.8V ²	75	150		
I _{BHH}	Bus hold HIGH sustaining current	V _{CC} = 2.3V; V _I = 1.7V ²	-45			μA
		V _{CC} = 3.0V; V _I = 2.0V ²	-75	-175		
I _{BHLO}	Bus hold LOW overdrive current	V _{CC} = 3.6V ²	500			μA
I _{BHHO}	Bus hold HIGH overdrive current	V _{CC} = 3.6V ²	-500			μA

NOTES:

1. All typical values are at T_{amb} = 25°C.
2. Valid for data inputs of bus hold parts.

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AC CHARACTERISTICS FOR $V_{CC} = 2.3V$ TO $2.7V$ RANGEGND = 0V; $t_r = t_f \leq 2.0ns$; $C_L = 30pF$

SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			$V_{CC} = 2.5V \pm 0.2V$			
			MIN	TYP ¹	MAX	
t_{PHL}/t_{PLH}	Propagation delay An, Bn to Bn, An	1, 2	1.0	2.8	5.1	ns
	Propagation delay LE _{AB} , LE _{BA} to Bn, An		1.1	3.5	6.1	
	Propagation delay CP _{AB} , CP _{BA} to Bn, An		1.0	3.3	6.1	
t_{PZH}/t_{PZL}	3-State output enable time OE _{BA} to An	3	1.3	2.8	6.3	ns
	3-State output enable time OE _{AB} to Bn		1.0	2.5	5.8	
t_{PHZ}/t_{PLZ}	3-State output enable time OE _{BA} to An	3	1.3	2.5	5.3	ns
	3-State output enable time OE _{AB} to Bn		1.5	2.5	6.2	
t_w	Pulse width HIGH LE _{AB} , LE _{BA}	2	3.3	0.8	–	ns
	Pulse width HIGH or LOW CP _{AB} , CP _{BA}		3.3	2.0	–	
t_{SU}	Set-up time An, Bn to CP _{AB} , CP _{BA}	4	1.7	0.1	–	ns
	Set-up time An, Bn to LE _{AB} , LE _{BA}		1.1	0.1	–	
t_h	Hold time An, Bn to CP _{AB} , CP _{BA}	4	1.7	0.3	–	ns
	Hold time An, Bn to LE _{AB} , LE _{BA}		1.6	0.3	–	
f_{MAX}	Maximum clock frequency		150	333	–	MHz

NOTE:1. All typical values are at $V_{CC} = 2.5V$ and $T_{amb} = 25^{\circ}C$.

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AC CHARACTERISTICS FOR $V_{CC} = 3.0V$ TO $3.6V$ RANGE AND $V_{CC} = 2.7V$ GND = 0V; $t_r = t_f = 2.5ns$; $C_L = 50pF$

SYMBOL	PARAMETER	WAVEFORM	LIMITS						UNIT
			$V_{CC} = 3.3V \pm 0.3V$			$V_{CC} = 2.7V$			
			MIN	TYP ¹	MAX	MIN	TYP	MAX	
t_{PHL}/t_{PLH}	Propagation delay An, Bn to Bn, An	1, 2	1.0	3.0	4.2		3.0	4.6	ns
	Propagation delay LE _{AB} , LE _{BA} to Bn, An		1.3	3.4	4.8		3.6	5.3	
	Propagation delay CP _{AB} , CP _{BA} to Bn, An		1.4	3.3	4.9		3.4	5.6	
t_{PZH}/t_{PZL}	3-State output enable time OE _{BA} to An	3	1.1	2.5	5.0		3.3	6.0	ns
	3-State output enable time OE _{AB} to Bn		1.0	2.4	4.6		2.7	5.3	
t_{PHZ}/t_{PLZ}	3-State output disable time OE _{BA} to An	3	1.3	3.1	4.2		3.3	4.6	ns
	3-State output disable time OE _{AB} to Bn		1.4	2.9	5.0		3.6	5.7	
t_w	LE pulse width LE _{AB} , LE _{BA} to CP _{AB} , CP _{BA}	2	3.3	0.9		3.3	0.7		ns
	LE pulse width HIGH or LOW CP _{AB} , CP _{BA}		3.3	1.1		3.3	1.4		
t_{SU}	Set-up time An, Bn to CP _{AB} , CP _{BA}	4	1.3	-0.3		1.4	-0.1		ns
	Set-up time An, Bn to LE _{AB} , LE _{BA}		1.0	0.3		1.0	-0.2		
t_h	Hold time An, Bn to CP _{AB} , CP _{BA}	4	1.3	0.4		1.6	0.3		ns
	Hold time An, Bn to LE _{AB} , LE _{BA}		1.2	0.1		1.5	0.1		
f_{MAX}	Maximum clock frequency		150	340		150	333		MHz

NOTE:1. All typical values are at $V_{CC} = 3.3V$ and $T_{amb} = 25^\circ C$.

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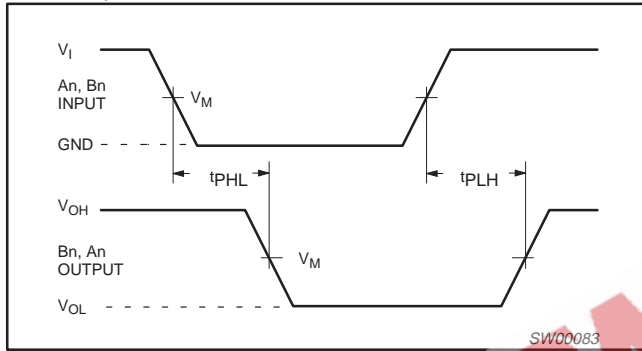
AC WAVEFORMS

V_{CC} = 2.3 TO 2.7 V RANGE

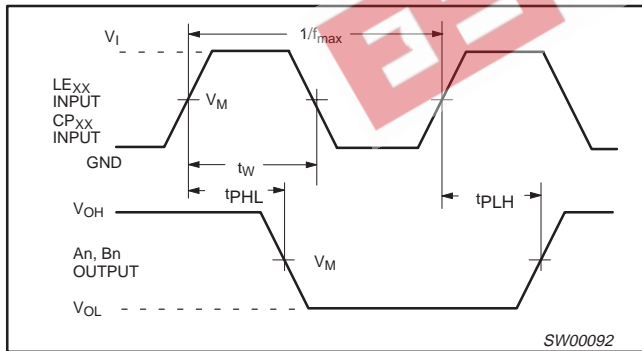
1. V_M = 0.5 V
2. V_X = V_{OL} + 0.15V
3. V_Y = V_{OH} - 0.15V
4. V_I = V_{CC}
5. V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

V_{CC} = 3.0 TO 3.6 V RANGE AND V_{CC} = 2.7 V

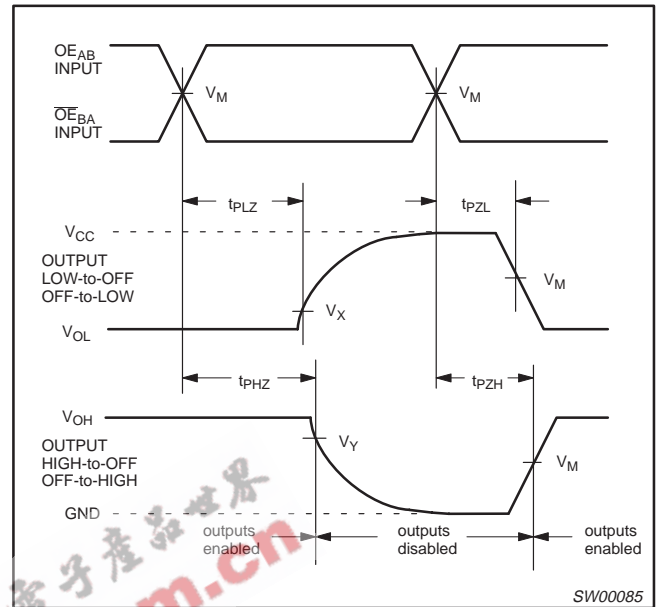
1. V_M = 1.5 V
2. V_X = V_{OL} + 0.3V
3. V_Y = V_{OH} - 0.3V
4. V_I = 2.7 V
5. V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.



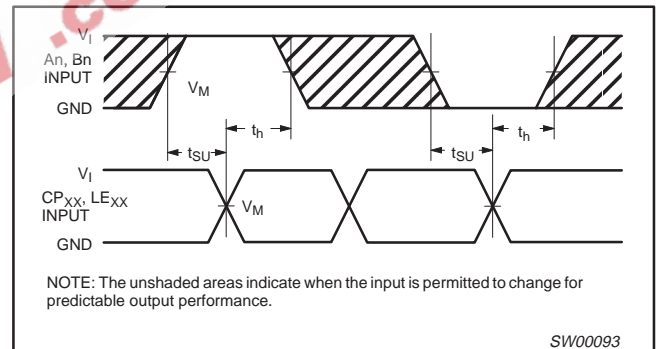
Waveform 1. Input (An, Bn) to output (Bn, An) propagation delays



Waveform 2. Latch enable input (LE_{AB}, LE_{BA}) and clock pulse input (CP_{AB}, CP_{BA}) to output propagation delays and their pulse width



Waveform 3. 3-State enable and disable times



Waveform 4. Data set-up and hold times for the An and Bn inputs to the LE_{AB}, LE_{BA}, CP_{AB} and CP_{BA} inputs

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TEST CIRCUIT

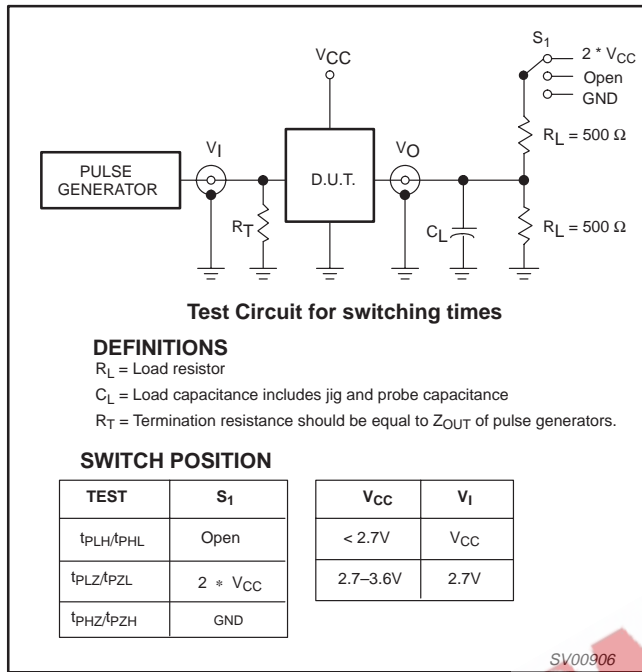
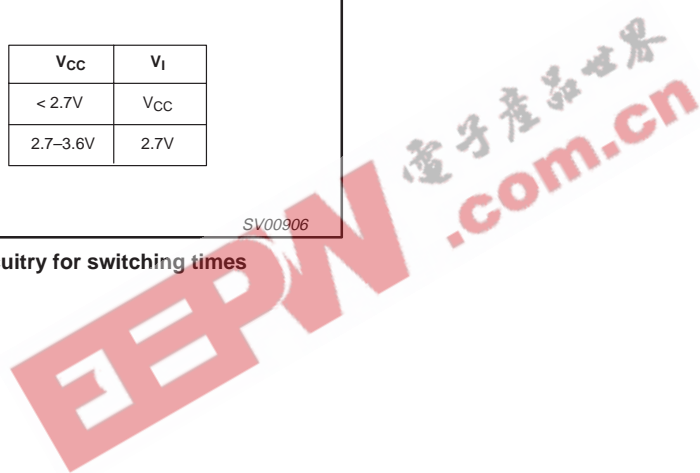


Figure 5. Load circuitry for switching times

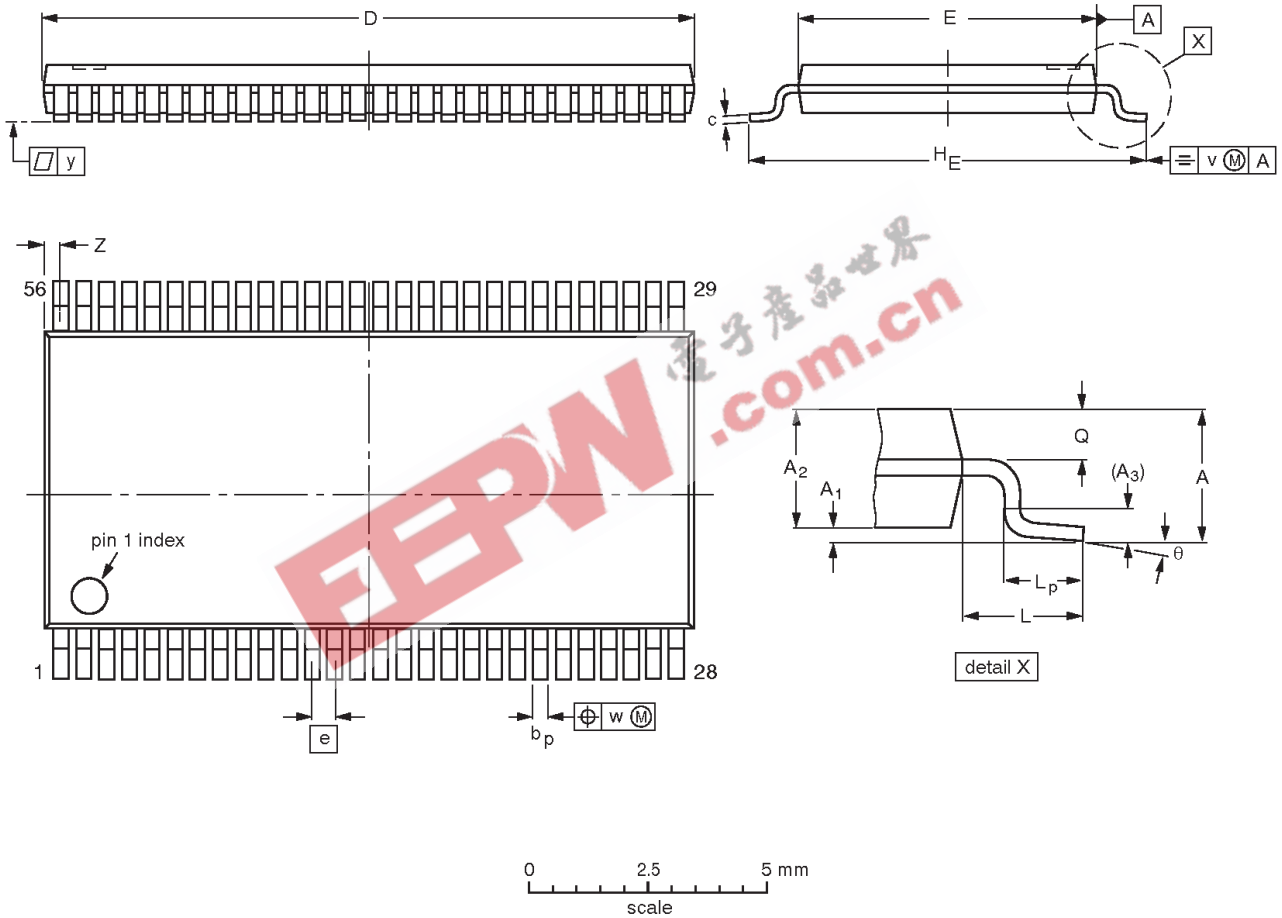


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TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1mm

SOT364-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1.0	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT364-1		MO-153EE				93-02-03 95-02-10

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NOTES



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DEFINITIONS

Data Sheet Identification	Product Status	Definition
<i>Objective Specification</i>	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
<i>Preliminary Specification</i>	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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